

Application Serial No. 10/630,034  
Amendment dated June 30, 2006  
Reply to Office communication of June 5, 2006

**Amendments to the Claims:**

The listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

Claims 1 to 39 (canceled without prejudice or disclaimer)

40. (previously presented): A process for coating a conductive substrate comprising:

(i) contacting said substrate with an aqueous composition in which the major component is water having polymerizable reactants dispersed in said water and an inorganic particulate carrier having a particle size less than 20 microns and having sorbed on said inorganic particulate carrier a catalyst for said polymerizable reactants, wherein said catalyst is a metal containing catalyst having a water solubility less than 1% by weight in water at 25° C. based upon the weight of metal in said catalyst and is a liquid when sorbed onto said inorganic particulate carrier;

(ii) passing an electric current between said substrate and a counter-electrode in electrical contact with said aqueous composition until a coating of a desired thickness is deposited from said composition onto said substrate to obtain a coated substrate;

(iii) removing said coated substrate from said aqueous composition; and

(iv) curing said coating.

42 to 52. (canceled without prejudice or disclaimer).